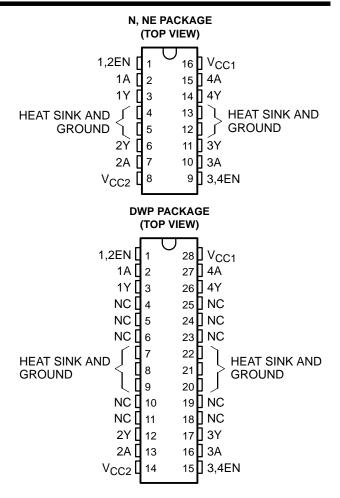
- Featuring Unitrode L293 and L293D
 Products Now From Texas Instruments
- Wide Supply-Voltage Range: 4.5 V to 36 V
- Separate Input-Logic Supply
- Internal ESD Protection
- Thermal Shutdown
- High-Noise-Immunity Inputs
- Functional Replacements for SGS L293 and SGS L293D
- Output Current 1 A Per Channel (600 mA for L293D)
- Peak Output Current 2 A Per Channel (1.2 A for L293D)
- Output Clamp Diodes for Inductive Transient Suppression (L293D)

description

The L293 and L293D are quadruple high-current half-H drivers. The L293 is designed to provide bidirectional drive currents of up to 1 A at voltages from 4.5 V to 36 V. The L293D is designed to provide bidirectional drive currents of up to 600-mA at voltages from 4.5 V to 36 V. Both devices are designed to drive inductive loads such as relays, solenoids, dc and bipolar stepping motors, as well as other high-current/high-voltage loads in positive-supply applications.



All inputs are TTL compatible. Each output is a complete totem-pole drive circuit, with a Darlington transistor sink and a pseudo-Darlington source. Drivers are enabled in pairs, with drivers 1 and 2 enabled by 1,2EN and drivers 3 and 4 enabled by 3,4EN. When an enable input is high, the associated drivers are enabled and their outputs are active and in phase with their inputs. When the enable input is low, those drivers are disabled and their outputs are off and in the high-impedance state. With the proper data inputs, each pair of drivers forms a full-H (or bridge) reversible drive suitable for solenoid or motor applications.

On the L293, external high-speed output clamp diodes should be used for inductive transient suppression.

A V_{CC1} terminal, separate from V_{CC2}, is provided for the logic inputs to minimize device power dissipation.

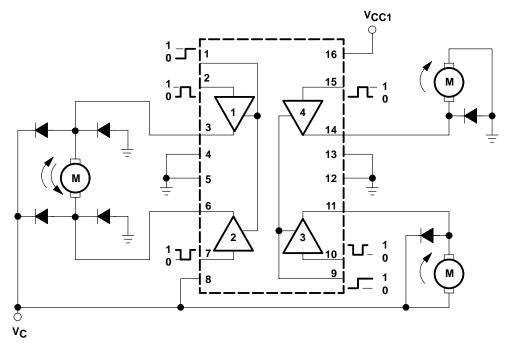
The L293and L293D are characterized for operation from 0°C to 70°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



block diagram



NOTE: Output diodes are internal in L293D.

TEXAS INSTRUMENTS AVAILABLE OPTIONS

	PACKAGE
TA	PLASTIC DIP (NE)
0°C to 70°C	L293NE L293DNE

Unitrode Products from Texas Instruments AVAILABLE OPTIONS

	PACKAGED DEVICES			
TA	SMALL OUTLINE (DWP)	PLASTIC DIP (N)		
0°C to 70°C	L293DWP L293DDWP	L293N L293DN		

The DWP package is available taped and reeled. Add the suffix TR to device type (e.g., L293DWPTR).

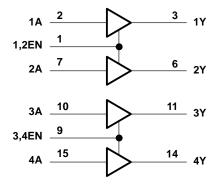


FUNCTION TABLE (each driver)

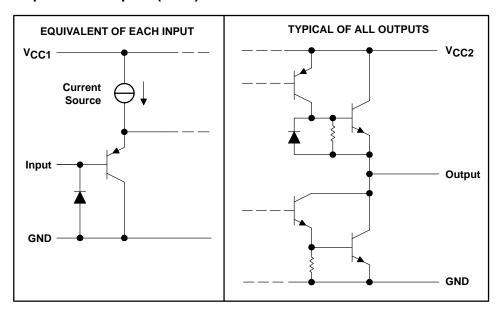
INP	итѕ†	OUTPUT
Α	EN	Y
Н	Н	Н
L	Н	L
X	L	Z

H = high level, L = low level, X = irrelevant, Z = high impedance (off)

logic diagram

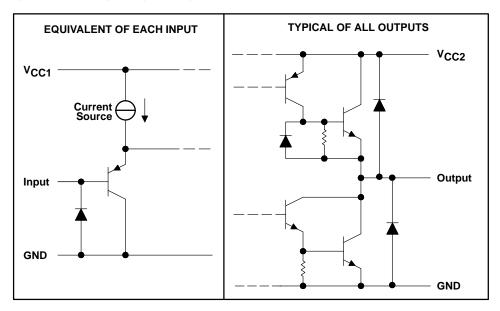


schematics of inputs and outputs (L293)



[†] In the thermal shutdown mode, the output is in the high-impedance state, regardless of the input levels.

schematics of inputs and outputs (L293D)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V _{CC1} (see Note 1)	36 V
Output supply voltage, V _{CC2}	
Input voltage, V _I	7 V
Output voltage range, V _O	$-3 \text{ V to V}_{CC2} + 3 \text{ V}$
Peak output current, I _O (nonrepetitive, t ≤ 5 ms): L293	±2 A
Peak output current, I _O (nonrepetitive, t ≤ 100 μs): L293D	±1.2 A
Continuous output current, IO: L293	±1 A
Continuous output current, IO: L293D	±600 mA
Continuous total dissipation at (or below) 25°C free-air temperature (see Notes 2 and 3)	2075 mW
Continuous total dissipation at 80°C case temperature (see Note 3)	5000 mW
Maximum junction temperature, T _J	150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltage values are with respect to the network ground terminal.
 - 2. For operation above 25°C free-air temperature, derate linearly at the rate of 16.6 mW/°C.
 - 3. For operation above 25°C case temperature, derate linearly at the rate of 71.4 mW/°C. Due to variations in individual device electrical characteristics and thermal resistance, the built-in thermal overload protection may be activated at power levels slightly above or below the rated dissipation.



recommended operating conditions

			MIN	MAX	UNIT
	Supply voltage V _C	CC1	4.5	7	V
	V _C	CC2	V _{CC1}	36	٧
\/	High-level input voltage	CC1 ≤ 7 V	2.3	V _{CC1}	V
VIH		CC1 ≥ 7 V	2.3	7	V
V _{IL} Low-level output voltage					V
T _A Operating free-air temperature					°C

[†] The algebraic convention, in which the least positive (most negative) designated minimum, is used in this data sheet for logic voltage levels.

electrical characteristics, V_{CC1} = 5 V, V_{CC2} = 24 V, T_A = 25°C

PARAMETER			TEST CONDITIONS		MIN	TYP	MAX	UNIT
VOH	High-level output voltage		L293: I _{OH} = -1 A L293D: I _{OH} = -0.6 A		V _{CC2} -1.8	V _{CC2} -1.4		V
VOL	Low-level output voltage			L293: I _{OL} = 1 A L293D: I _{OL} = 0.6 A		1.2	1.8	V
Vокн	High-level output clamp vo	oltage	L293D: I _{OK} :	=-0.6 A		V _{CC2} + 1.3		V
VOKL	Low-level output clamp vo	ltage	L293D: I _{OK} = 0.6 A			1.3		V
Ī	A A		V. 7.V			0.2	100	
I 'IH	I _{IH} High-level input current	EN	V _I = 7 V			0.2	10	μΑ
I	Low lovel input ourrent	А	\/ 0			-3	-10	
'IL	I _{IL} Low-level input current		V _I = 0			-2	-100	μΑ
				All outputs at high level		13	22	
ICC1	Logic supply current		IO = 0	All outputs at low level		35	60	mA
				All outputs at high impedance		8	24	
				All outputs at high level		14	24	
ICC2	2 Output supply current		IO = 0	All outputs at low level		2	6	mA
				All outputs at high impedance		2	4	

switching characteristics, V_{CC1} = 5 V, V_{CC2} = 24 V, T_A = 25°C

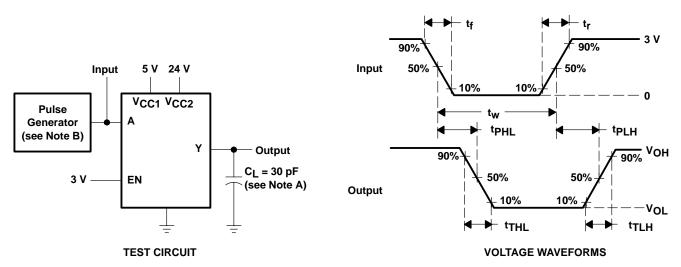
	PARAMETER	TEST CONDITIONS	L293NE, L293DNE			UNIT
	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	ONIT
^t PLH	Propagation delay time, low-to-high-level output from A input			800		ns
tPHL	Propagation delay time, high-to-low-level output from A input	Cr = 20 pE Soo Figure 1		400		ns
tTLH	Transition time, low-to-high-level output	C _L = 30 pF, See Figure 1		300		ns
tTHL	Transition time, high-to-low-level output			300		ns

switching characteristics, V_{CC1} = 5 V, V_{CC2} = 24 V, T_A = 25°C

	PARAMETER	TEST CONDITIONS	L293DWP, L293N L293DDWP, L293DN			UNIT
			MIN	TYP	MAX	
tPLH	Propagation delay time, low-to-high-level output from A input			750		ns
^t PHL	Propagation delay time, high-to-low-level output from A input	C _I = 30 pF, See Figure 1		200		ns
^t TLH	Transition time, low-to-high-level output	CL = 30 pr, See rigule i		100		ns
^t THL	Transition time, high-to-low-level output			350		ns



PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

B. The pulse generator has the following characteristics: $t_r \le 10$ ns, $t_f \le 10$ ns, $t_W = 10$ μ s, PRR = 5 kHz, $Z_O = 50$ Ω .

Figure 1. Test Circuit and Voltage Waveforms

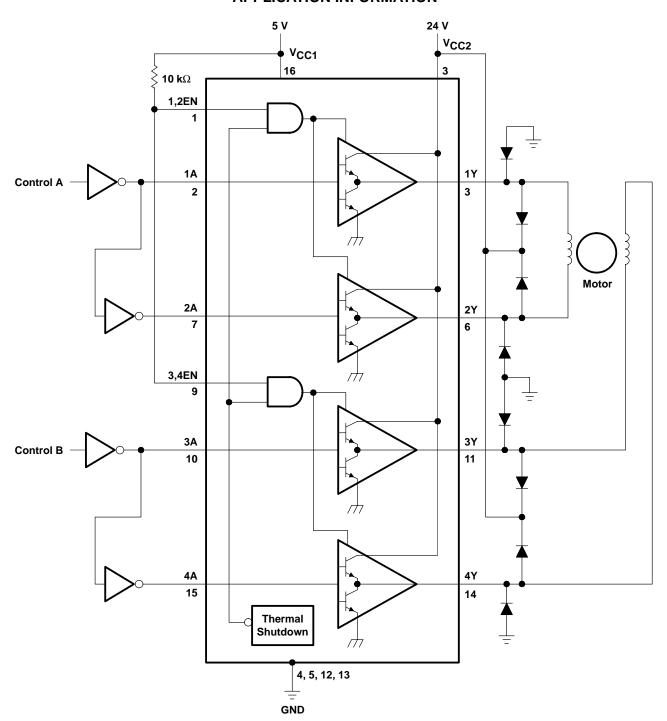


Figure 2. Two-Phase Motor Driver (L293)

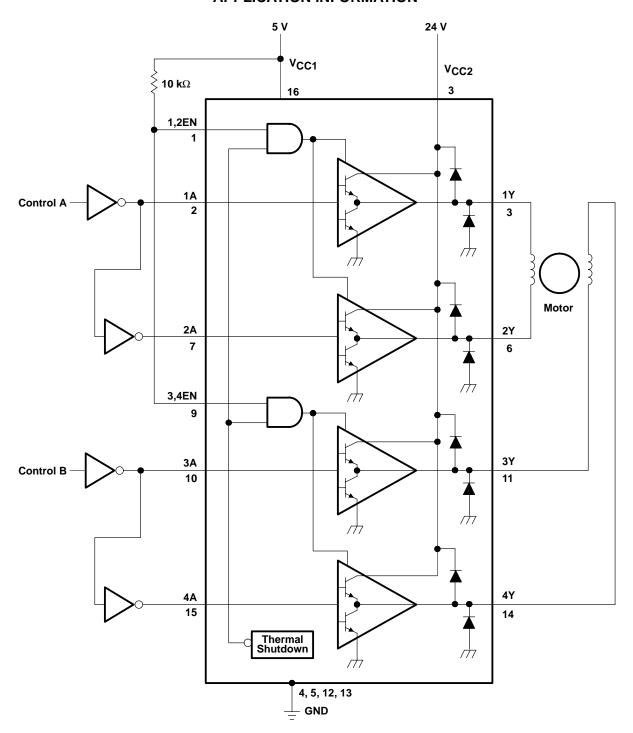
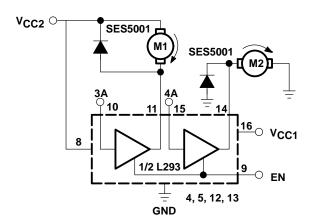


Figure 3. Two-Phase Motor Driver (L293D)





EN	3A	M1	4A	M2
Н	Н	Fast motor stop	Н	Run
Н	L	Run	L	Fast motor stop
L	Х	Free-running motor stop	Х	Free-running motor stop

L = low, H = high, X = don't care

Figure 4. DC Motor Controls (connections to ground and to supply voltage)

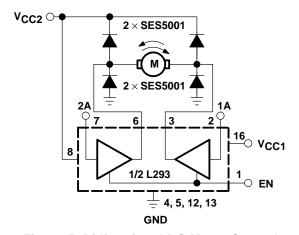
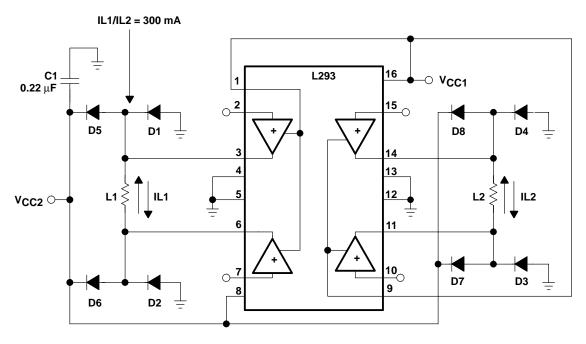


Figure 5. Bidirectional DC Motor Control

EN	1A	2A	FUNCTION
Н	L	Н	Turn right
Н	Н	L	Turn left
Н	L	L	Fast motor stop
Н	Н	Н	Fast motor stop
L	Х	Х	Fast motor stop

L = low, H = high, X = don't care





D1-D8 = SES5001

Figure 6. Bipolar Stepping-Motor Control

mounting instructions

The Rthj-amp of the L293 can be reduced by soldering the GND pins to a suitable copper area of the printed circuit board or to an external heatsink.

Figure 9 shows the maximum package power P_{TOT} and the θ_{JA} as a function of the side ℓ of two equal square copper areas having a thickness of 35 μ m (see Figure 7). In addition, an external heat sink can be used (see Figure 8).

During soldering, the pin temperature must not exceed 260°C, and the soldering time must not be longer than 12 seconds.

The external heatsink or printed circuit copper area must be connected to electrical ground.



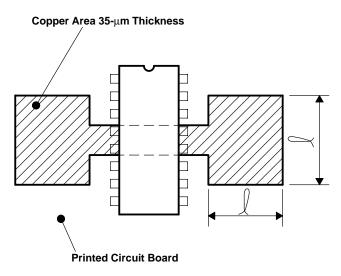


Figure 7. Example of Printed Circuit Board Copper Area (used as heat sink)

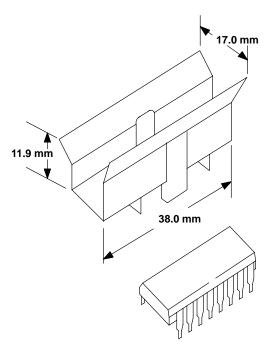
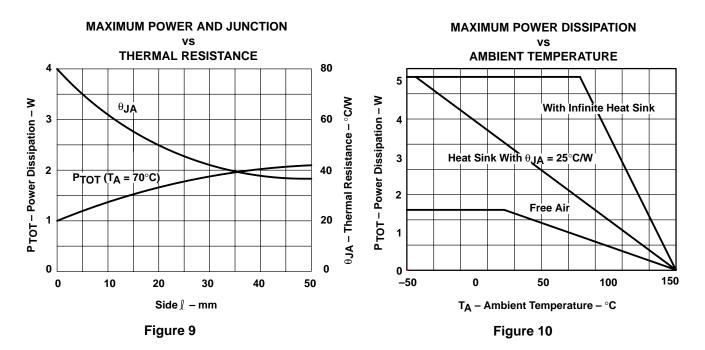


Figure 8. External Heat Sink Mounting Example ($\theta_{JA} = 25^{\circ}\text{C/W}$)



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